

Features

- SMD filter consisting of coupled resonators with stepped impedances
- (NdBa)TiO₃ ($\epsilon_r = 88$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10 μ m) and tin (>5 μ m)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

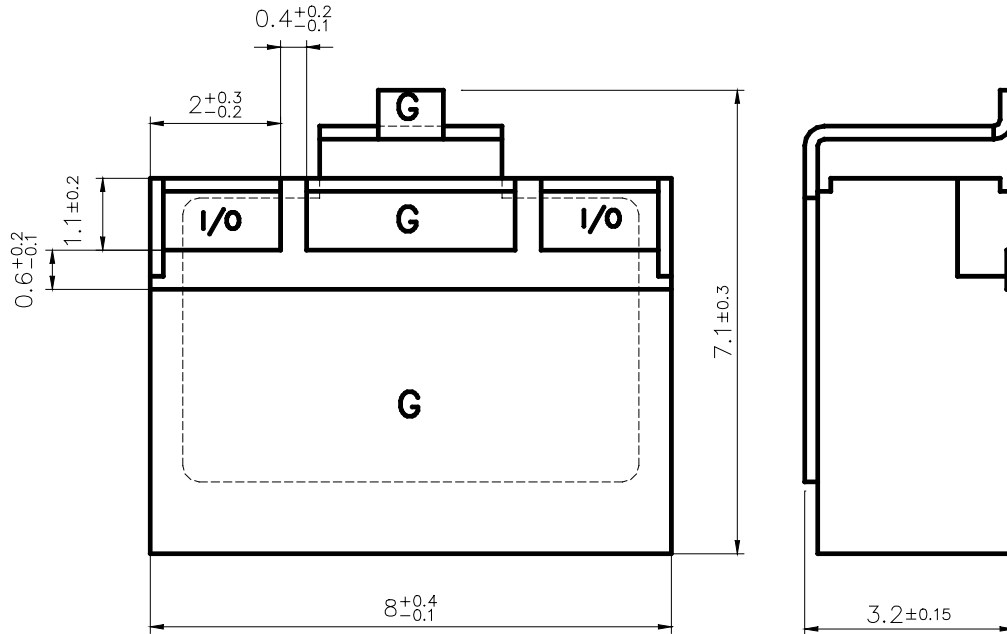
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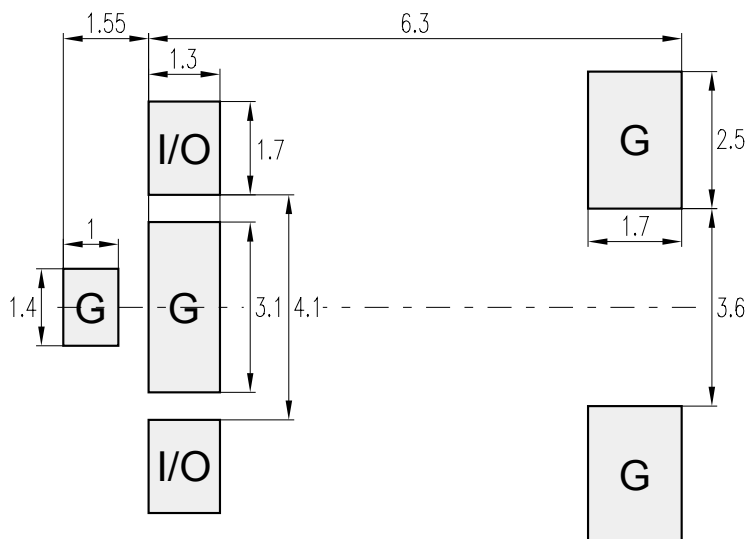
Preliminary Data Sheet

Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint





Preliminary Data Sheet

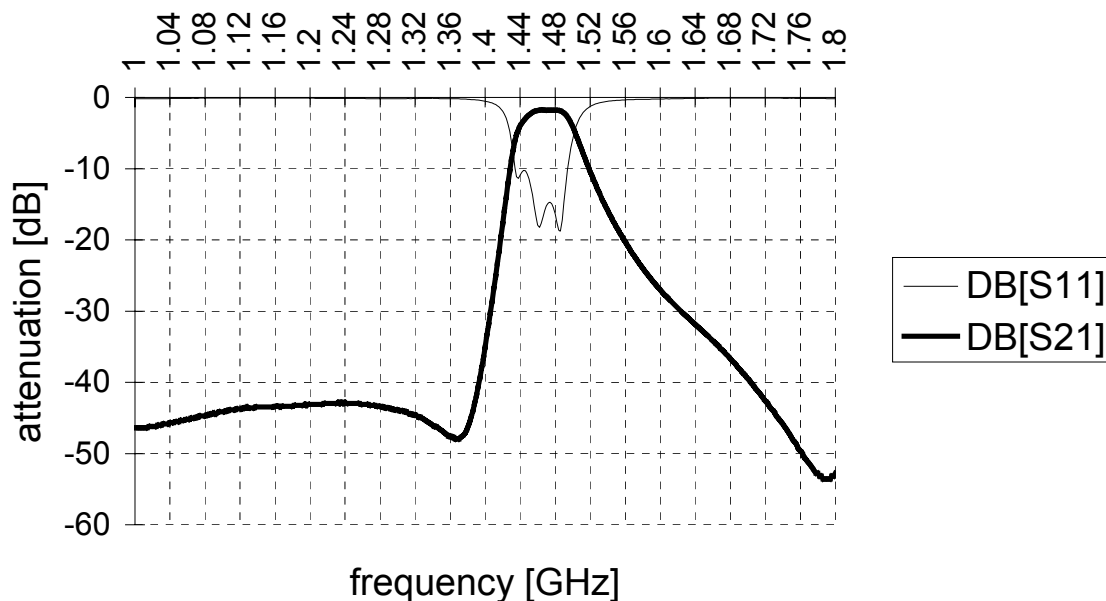
Characteristics

| | | min. | typ. | max. | |
|--------------------------------|---------------------|------|------|------|----------|
| Center frequency | f_c | - | 1472 | - | MHz |
| Insertion loss | α_{IL} | | 1.8 | 2.3 | dB |
| Passband | B | 40 | | | MHz |
| 1dB Bandwidth | | | 60 | | MHz |
| Amplitude ripple (peak - peak) | $\Delta\alpha$ | | 0.3 | 1.0 | dB |
| Standing wave ratio | SWR | | 1.5 | 2.0 | |
| Impedance | Z | | 50 | | Ω |
| Attenuation | α | | | | |
| | DC to 1262 MHz | 40 | 47 | | dB |
| | at 1262 to 1350 MHz | 30 | 35 | | dBc |
| | at 1350 to 1380 MHz | 25 | 28 | | dB |
| | at 1380 to 1400 Mhz | 15 | 18 | | dB |
| | at 1660 MHz | 30 | 31 | | dBc |

Maximum ratings

| | | | |
|----------------------------------|----------|--------------|----|
| IEC climatic category (IEC 68-1) | | - 40/+ 90/56 | |
| Operating temperature | T_{op} | - 20 / + 85 | °C |

Typical passband characteristic



3-Pole Filter for WSP

B69813N1477A840

Preliminary Data Sheet

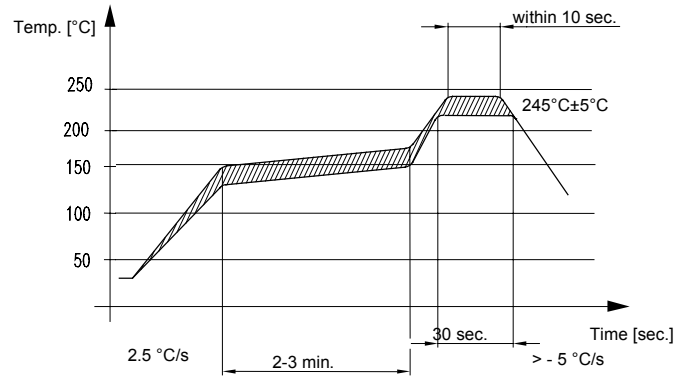
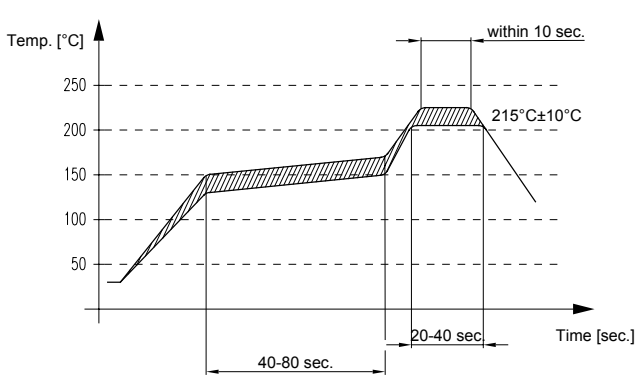
Processing information

- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

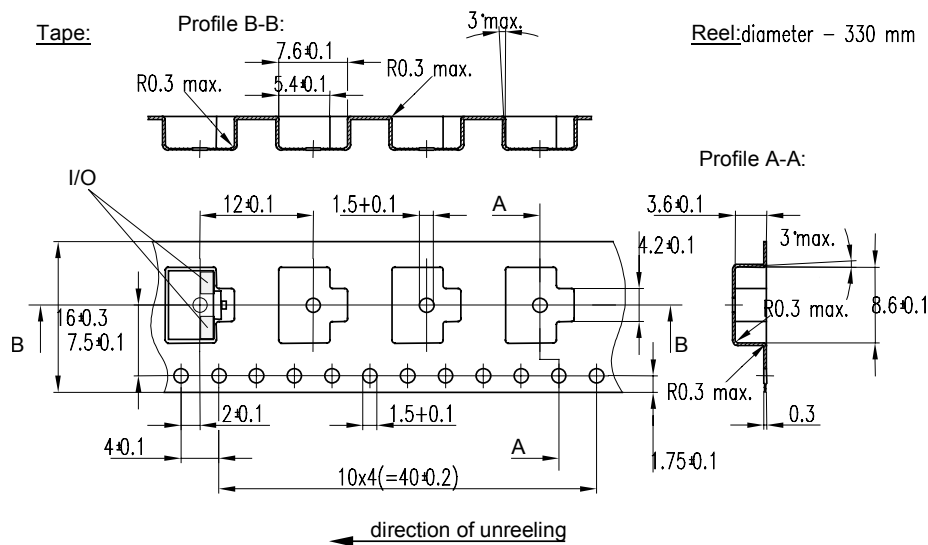
| | Profile for eutectic SnPb solder paste | Profile for leadfree solder paste | |
|---|---|---|----------|
| Soldering type | reflow | reflow | |
| Maximum soldering temperature (measuring point on top surface of the component) | 235 (max. 2 sec.) 225 (max. 10 sec.) | 260 (max. 2 sec.) 250 (max. 10 sec.) | °C °C |

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape to IEC 286-3, polystyrol, grey
- Pieces/tape: 1500



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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